

# **TECHNICAL DATASHEET**



# **Brazing alloy BrazeTec Soldamoll 300**

**TD EN SLDM300** 

## Composition (% in weight)

Ag	Cu	Zn	Sn	Si	Р	Mn	Ni	Other	ISO 17672:20 10	EN 1044:1999	ISO 3677
10	-	-	90	-	-	-	-	-	-	-	S-Sn90Ag10

#### **Technical data:**

Melting range (°C)	221 - 300			
Working temperature (°C)	-			
Melting range according to DSC measurement (°C)	-			
Min. brazing temperature (°C)	-			
Electrical conductibility (m/Ω mm²)	7,5			
Elongation %	-			
Density (g/cm³)	7,5			
Shear strength (MPa)	-			
Tensile strength DIN EN 12797 (MPa)	Cu: 30; Brass: 20 ; S235: 25			
Operating temperature of brazed joint (min/max) $\pm$ (°C)	-			

#### **Applications**

Plumbing technology, electrical industry

## **Operating conditions**

Tin based brazing alloy, free from antimony and lead. Excellent flow, capillarity and mechanical strength characteristics. Used for joining steel, copper and copper alloys, as well as nickel and nickel alloys. Suitable for copper pipes installations for plumbing system.

## **Recommended fluxes**

Soldaflux 7000

#### **Heat sources**

Flame, induction heating, resistance

### **Delivery forms**

Wire

#### Notes-

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